INTEGRATED CIRCUITS

DATA SHEET

74LVT323.3 V Quad 2-input OR gate

Product data Supersedes data of 1996 Aug 28 2002 Sep 06





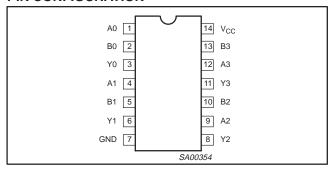
3.3 V Quad 2-input OR gate

74LVT32

QUICK REFERENCE DATA

SYMBOL	PARAMETER	TYPICAL	UNIT	
t _{PLH}	Propagation delay An, Bn to Yn	C _L = 50 pF; V _{CC} = 3.3 V	2.6 3.2	ns
C _{IN}	Input capacitance	V _I = 0 V or 3.0 V	3	pF
I _{CCL}	Total supply current	Outputs Low; V _{CC} = 3.6 V	1	mA

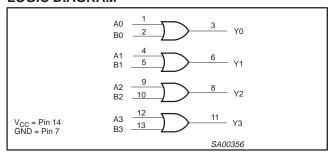
PIN CONFIGURATION



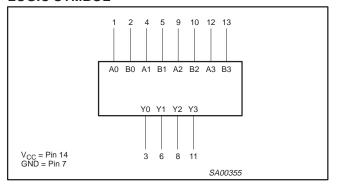
PIN DESCRIPTION

PIN NUMBER	SYMBOL	NAME AND FUNCTION
1, 2, 4, 5, 9, 10, 12, 13	An, Bn	Data inputs
3, 6, 8, 11 Yn		Data outputs
7	GND	Ground (0 V)
14	V _{CC}	Positive supply voltage

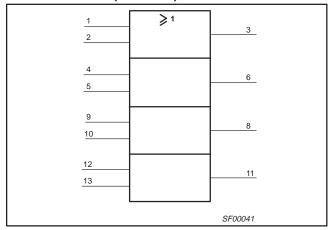
LOGIC DIAGRAM



LOGIC SYMBOL



LOGIC SYMBOL (IEEE/IEC)



FUNCTION TABLE

INP	UTS	OUTPUT					
Dna	Dnb	Qn					
L	L	L					
L	Н	Н					
Н	L	Н					
Н	Н	Н					

NOTES:

H = High voltage level L = Low voltage level

ORDERING INFORMATION

<u> </u>				
PACKAGES	TEMPERATURE RANGE	OUTSIDE NORTH AMERICA	NORTH AMERICA	DWG NUMBER
14-Pin Plastic SO	–40 °C to +85 °C	74LVT32D	74LVT32D	SOT108-1
14-Pin Plastic SSOP	−40 °C to +85 °C	74LVT32DB	74LVT32DB	SOT337-1
14-Pin Plastic TSSOP	–40 °C to +85 °C	74LVT32PW	74LVT32PWDH	SOT402-1

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ABSOLUTE MAXIMUM RATINGS1, 2

SYMBOL	PARAMETER	CONDITIONS	RATING	UNIT
V _{CC}	DC supply voltage		-0.5 to +4.6	V
I _{IK}	DC input diode current	V _I < 0	-50	mA
VI	DC input voltage ³		-0.5 to +7.0	V
lok	DC output diode current	V _O < 0	-50	mA
V _{OUT}	DC output voltage ³	Output in Off or High state	-0.5 to +7.0	V
1	DC output ourront	Output in High state	-32	mA
Гоит	DC output current	Output in Low state	64	IIIA
T _{stg}	Storage temperature range		-65 to 150	°C

NOTES:

RECOMMENDED OPERATING CONDITIONS

SYMBOL	PARAMETER	LIM	UNIT	
STIMBUL	PARAMETER	MIN	MAX	UNII
V _{CC}	DC supply voltage	2.7	3.6	V
V _I	Input voltage	0	5.5	V
V _{IH}	High-level input voltage	2.0		V
V _{IL}	Low-level Input voltage		0.8	V
I _{OH}	High-level output current		-20	mA
I _{OL}	Low-level output current		32	mA
Δt/Δν	Input transition rise or fall rate; Outputs enabled		10	ns/V
T _{amb}	Operating free-air temperature range	-40	+85	°C

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^{1.} Stresses beyond those listed may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

The performance capability of a high-performance integrated circuit in conjunction with its thermal environment can create junction temperatures which are detrimental to reliability. The maximum junction temperature of this integrated circuit should not exceed 150°C.

3. The input and output negative voltage ratings may be exceeded if the input and output clamp current ratings are observed.

74LVT32

DC ELECTRICAL CHARACTERISTICS

Over recommended operating conditions Voltages are referenced to GND (ground = 0 V)

			ı		UNIT	
SYMBOL	PARAMETER	TEST CONDITIONS	Temp = -	+85°C		
			MIN	TYP ¹	MAX	
V _{IK}	Input clamp voltage	V _{CC} = 2.7 V; I _{IK} = -18 mA			-1.2	V
		$V_{CC} = 2.7 \text{ to } 3.6 \text{ V}; I_{OH} = -100 \mu\text{A}$	V _{CC} -0.2			
V _{OH}	High-level output voltage	$V_{CC} = 2.7 \text{ V; } I_{OH} = -6 \text{ mA}$	2.4			V
		$V_{CC} = 3.0 \text{ V}; I_{OH} = -20 \text{ mA}$	2.0			
		$V_{CC} = 2.7 \text{ V}; I_{OL} = 100 \mu\text{A}$			0.2	
V _{OL}	Low-level output voltage	V _{CC} = 2.7 V; I _{OL} = 24 mA			0.5	V
		V _{CC} = 3.0 V; I _{OL} = 32 mA			0.5	
l ₁	Input leakage current V _{CC} = 0 or 3.6 V; V _I = 5.5 V				10	μА
"	input leakage culterit	$V_{CC} = 3.6 \text{ V}; V_I = V_{CC} \text{ or GND}$			±1	μΑ
l _{OFF}	Output off current	$V_{CC} = 0 \text{ V}; V_{I} \text{ or } V_{O} = 0 \text{ to } 4.5 \text{ V}$			±100	μА
Іссн	Quiescent supply current	$V_{CC} = 3.6 \text{ V};$ Outputs High, $V_I = \text{GND or } V_{CC}, I_O = 0$			0.02	mA
I _{CCL}	Quiescent supply current	$V_{CC} = 3.6 \text{ V};$ Outputs Low, $V_I = \text{GND or } V_{CC}, I_O = 0$		1	2	ША
Δl _{CC}	Additional supply current per input pin ²	V_{CC} = 3 V to 3.6 V; One input at V_{CC} -0.6 V, Other inputs at V_{CC} or GND			0.2	μА
C _I	Input capacitance	$V_1 = 3 V \text{ or } 0$		3		pF

NOTES:

- 1. All typical values are at V_{CC} = 3.3 V and T_{amb} = 25 °C. 2. This is the increase in supply current for each input at the specificed voltage level other than V_{CC} or GND.

AC CHARACTERISTICS

GND = 0 V; $t_R = t_F$ = 2.5 ns; C_L = 50 pF, R_L = 500 Ω ; T_{amb} = -40 °C to +85 °C.

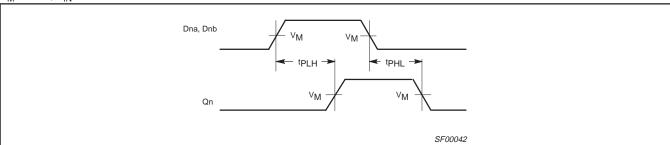
SYMBOL	PARAMETER	WAVEFORM	V _{CC}	= 3.3 V \pm 0	V _{CC} = 2.7 V	UNIT	
			MIN	TYP ¹	MAX	MAX	
t _{PLH} t _{PHL}	Propagation delay An, Bn to Yn	1	1.0 1.0	2.6 3.2	3.8 4.6	4.5 4.9	ns

NOTE:

1. All typical values are at V_{CC} = 3.3 V and T_{amb} = 25 $^{\circ}C.$

AC WAVEFORMS

 $V_M = 1.5 \text{ V}, V_{IN} = \text{GND to } 2.7 \text{ V}$

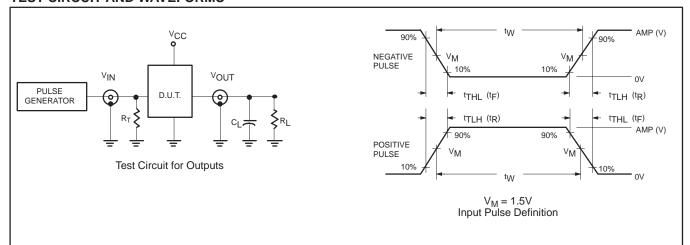


Waveform 1. Propagation delay for inverting outputs

3.3 V Quad 2-input OR gate

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TEST CIRCUIT AND WAVEFORMS



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DEFINITIONS

 R_L = Load resistor; see AC CHARACTERISTICS for value.

 $C_L = Load$ capacitance includes jig and probe capacitance; see AC CHARACTERISTICS for value.

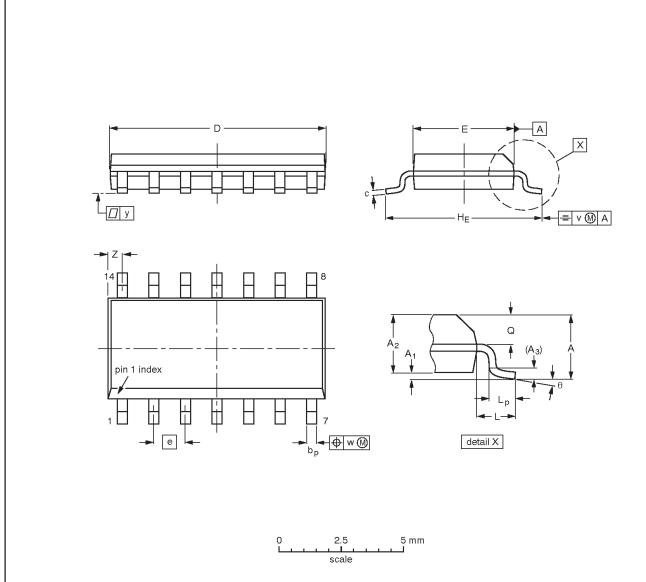
FAMILY	INPUT PULSE REQUIREMENTS											
FAMILI	Amplitude	Rep. Rate	t _W	t _R	t _F							
74LVT	2.7V	≤10MHz	500ns	≤2.5ns	≤2.5ns							

SV00022

74LVT32

SO14: plastic small outline package; 14 leads; body width 3.9 mm

SOT108-1



DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A ₁	A ₂	A ₃	bp	С	D ⁽¹⁾	E ⁽¹⁾	е	HE	L	Lp	Q	v	w	у	Z ⁽¹⁾	θ
mm	1.75	0.25 0.10	1.45 1.25	0.25	0.49 0.36	0.25 0.19	8.75 8.55	4.0 3.8	1.27	6.2 5.8	1.05	1.0 0.4	0.7 0.6	0.25	0.25	0.1	0.7 0.3	8°
inches	0.069	0.010 0.004	0.057 0.049	0.01		0.0100 0.0075	0.35 0.34	0.16 0.15	0.050	0.244 0.228	0.041	0.039 0.016	0.028 0.024	0.01	0.01	0.004	0.028 0.012	0°

Note

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.

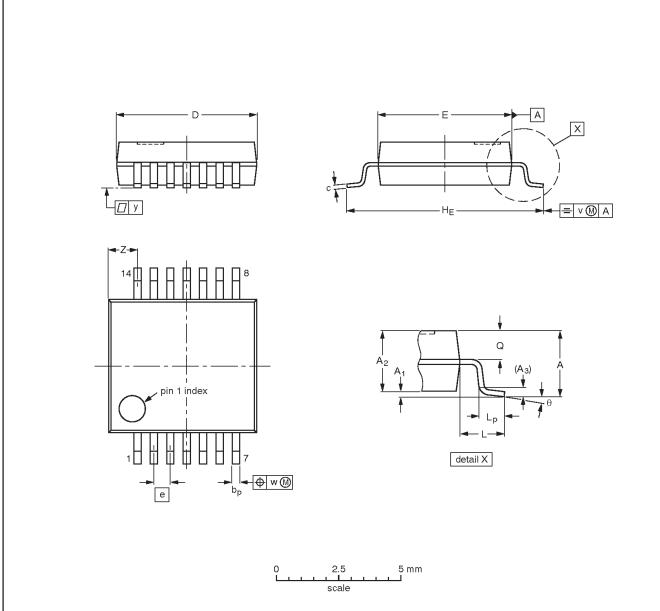
OUTLINE		REFER	EUROPEAN	ISSUE DATE		
VERSION	IEC	JEDEC	EIAJ		PROJECTION	ISSUE DATE
SOT108-1	076E06	MS-012				97-05-22 99-12-27

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SSOP14: plastic shrink small outline package; 14 leads; body width 5.3 mm

SOT337-1



DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A ₁	A ₂	A ₃	bp	С	D ⁽¹⁾	E ⁽¹⁾	e	HE	L	Lp	Q	v	w	у	Z ⁽¹⁾	θ
mm	2.0	0.21 0.05	1.80 1.65	0.25	0.38 0.25	0.20 0.09	6.4 6.0	5.4 5.2	0.65	7.9 7.6	1.25	1.03 0.63	0.9 0.7	0.2	0.13	0.1	1.4 0.9	8° 0°

Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

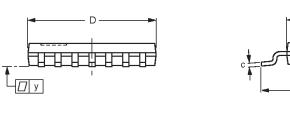
OUTLINE	OUTLINE REFERENCES					ISSUE DATE	
VERSION	IEC	JEDEC	EIAJ		PROJECTION	ISSUE DATE	
SOT337-1		MO-150				-96-01-18 99-12-27	

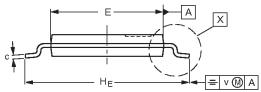
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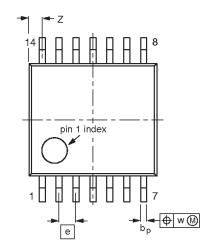
74LVT32

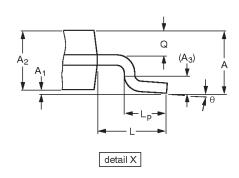
TSSOP14: plastic thin shrink small outline package; 14 leads; body width 4.4 mm

SOT402-1











DIMENSIONS (mm are the original dimensions)

UN	IT ,	A max.	Α1	A ₂	A ₃	bp	C	D ⁽¹⁾	E ⁽²⁾	e	HE	L	Lp	œ	٧	w	у	Z ⁽¹⁾	θ
m	n	1.10	0.15 0.05	0.95 0.80	0.25	0.30 0.19	0.2 0.1	5.1 4.9	4.5 4.3	0.65	6.6 6.2	1.0	0.75 0.50	0.4 0.3	0.2	0.13	0.1	0.72 0.38	8° 0°

Notes

- 1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.
- 2. Plastic interlead protrusions of 0.25 mm maximum per side are not included.

OUTLINE						ISSUE DATE	
VERSION	IEC	JEDEC	EIAJ		PROJECTION	ISSUE DATE	
SOT402-1		MO-153				-95-04-04 99-12-27	

3.3 V Quad 2-input OR gate

74LVT32

REVISION HISTORY

Rev	Date	Description
_2	2002 Sep 06	Product data (9397 750 10298); supersedes Product specification 74LVT32 of 1996 Aug 28.
		Modifications: There are no changes to any data. Document re-issued to improve quality of package outline drawings display only.
_	1996 Aug 28	Product specification; initial version. Engineering Change Notice: 853-1873 17244 (date: 1996 Aug 28).

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3.3 V Quad 2-input OR gate

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Data sheet status

Data sheet status ^[1]	Product status ^[2]	Definitions
Objective data	Development	This data sheet contains data from the objective specification for product development. Philips Semiconductors reserves the right to change the specification in any manner without notice.
Preliminary data	Qualification	This data sheet contains data from the preliminary specification. Supplementary data will be published at a later date. Philips Semiconductors reserves the right to change the specification without notice, in order to improve the design and supply the best possible product.
Product data	Production	This data sheet contains data from the product specification. Philips Semiconductors reserves the right to make changes at any time in order to improve the design, manufacturing and supply. Changes will be communicated according to the Customer Product/Process Change Notification (CPCN) procedure SNW-SQ-650A.

^[1] Please consult the most recently issued data sheet before initiating or completing a design.

Definitions

Short-form specification — The data in a short-form specification is extracted from a full data sheet with the same type number and title. For detailed information see the relevant data sheet or data handbook.

Limiting values definition — Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 60134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

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Date of release: 09-02

Document order number: 9397 750 10298

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^[2] The product status of the device(s) described in this data sheet may have changed since this data sheet was published. The latest information is available on the Internet at URL http://www.semiconductors.philips.com.